



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-11-03
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	T3DZ*OD64R52	A	3068	2017-11-03
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.1-4.5	3	THROUGH HOLE	
Comment	Package: TO 220 AB NON ISOL - MDF valid for CPs: STP100N6F7 and STP100N6			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.51	Die /Leadframe	268
Lead	3.05	Soft solder	1604

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	T3D2*OD64R52									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	0.994	mg	supplier	die	Silicon (Si)	7440-21-3		0.863	mg	868209	454				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.057	mg	57344	30				
				supplier	metallization	Silver (Ag)	7440-22-4		0.008	mg	8048	4				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	6036	3				
				supplier	metallization	Tungsten (W)	7440-33-7		0.014	mg	14085	7				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.014	mg	14085	7				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	2012	1				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.020	mg	20121	11				
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	2012	1				
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.008	mg	8048	4				
				Leadframe	Copper & its alloys	1253.535	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.376	mg	998278	658619
								supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	1000	659
								supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	300	198
supplier	metallization	Nickel (Ni)	7440-02-0						0.490	mg	390	258				
supplier	metallization	Phosphorus (P)	12185-10-3						0.040	mg	32	21				
Soft solder	Solder	3.191	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	3.047	mg	954873	1604				
				supplier	solder	Silver (Ag)	7440-22-4		0.080	mg	25071	42				
				supplier	solder	Tin (Sn)	7440-31-5		0.064	mg	20056	34				
Bonding wires	Other inorganic materials	1.765		supplier	wire	Aluminium (Al)	7429-90-5		1.758	mg	996034	925				
				supplier	wire	Magnesium (Mg)	7439-95-4		0.007	mg	3966	4				
Encapsulation	Other Organic Materials	634.153	mg	supplier	mold compound	Silica, vitreous	60676-86-0		551.713	mg	870000	290375				
				supplier	mold compound	Epoxy resin	25068-38-6		63.415	mg	100000	33376				
				supplier	mold compound	Phenol resin	29690-82-2		15.854	mg	25000	8346				
				supplier	mold compound	Carbon Black	1333-86-4		3.171	mg	5000	1669				
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348				